



DEVICE TYPE:				SEMPAC, INC. Open-Pak™ Technologies www.sempac.com 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006				
CUSTOMER:			DIE SIZE:					
WIRE TYPE/ SIZE:			NO. OF WIRES:					
THIRD ANGLE PROJECTION UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER DO NOT SCALE DRAWING	REVISIONS					12 Lead 3mm x 3mm MLP Open-Pak Bonding Diagram		
	ECN NO.	DATE	DESCRIPTION	APPROVED				
	10603	2/10/06	PRODUCTION RELEASE	D.BENANDO		SIZE	PART NO.	REV
DRAWN BY	W. GRIFFITTS	DATE	2/10/06	PACKAGE SIZE:	3.00mm x 3.00mm	A	MLP3X3-12-OP-01	1
APP BY	P. FLASKERUD	DATE	2/10/06	DIE PAD SIZE:	1.36mm x 1.36mm	SCALE 50X	CAD FILE	SHEET 1 OF 1
						MLP3X3-12-OP-01-B-R1.DWG		